

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Joanna Chaw Yane Yin</td> <td>07/25/2012</td> </tr> <tr> <td>Chi-Hsi Wu</td> <td>07/25/2012</td> </tr> <tr> <td>Kuo-Chiang Ting</td> <td>07/25/2012</td> </tr> </tbody> </table>		Name	Execution Date	Joanna Chaw Yane Yin	07/25/2012	Chi-Hsi Wu	07/25/2012	Kuo-Chiang Ting	07/25/2012				
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<table border="1"> <tr> <td>Name:</td> <td>Taiwan Semiconductor Manufacturing Company Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>No. 8, Li-Hsin Rd. 6</td> </tr> <tr> <td>Internal Address:</td> <td>Science-Based Industrial Park</td> </tr> <tr> <td>City:</td> <td>Hsin-Chu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	Taiwan Semiconductor Manufacturing Company Ltd.	Street Address:	No. 8, Li-Hsin Rd. 6	Internal Address:	Science-Based Industrial Park	City:	Hsin-Chu	State/Country:	TAIWAN	Postal Code:	300-77
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PROPERTY NUMBERS Total: 1													
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13490108</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13490108								
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Application Number:	13490108												
CORRESPONDENCE DATA													
<p>Fax Number: 2214200085          Phone: 214-651-5000          Email: ipdocketing@haynesboone.com  <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i></p> <p>Correspondent Name: Haynes and Boone LLP          Address Line 1: 2323 Victory Avenue          Address Line 2: Suite 700          Address Line 4: Dallas, TEXAS 75201</p>													
ATTORNEY DOCKET NUMBER:	24061.2050/2011-1215												
NAME OF SUBMITTER:	David M. O'Dell												
Total Attachments: 3 source=2050Assignment#page1.tif source=2050Assignment#page2.tif source=2050Assignment#page3.tif													

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Docket No.: 2011-1215 / 24061.2050  
Customer No.: 42717

### ASSIGNMENT

WHEREAS, we,

- |     |                         |   |
|-----|-------------------------|---|
| (1) | Joanna Chaw Yane Yin of | No. 168, Science Park 2nd Road<br>Hsinchu 300, R.O.C.             |
| (2) | Chi-Hsi Wu of           | No. 26, Lane 862, Nan-Da Road<br>Hsinchu City 300, Taiwan, R.O.C. |
| (3) | Kuo-Chiang Ting of      | 12F-3, No 90, Daxue Road<br>Hsinchu City 300, Taiwan, R.O.C.      |
| (4) | Kuang Hsin Chen of      | 440, Chun-Fu Road<br>Jung-Li City, Taiwan, R.O.C.                 |

have invented certain improvements in

### METHOD OF MAKING A FINFET DEVICE

for which we have filed and executed an application for Letters Patent of the United States of America on June 6, 2012, as U.S. Serial No. 13/490,108; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue

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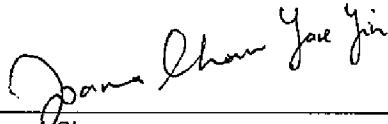
applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

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Inventor Name: Joanna Chaw Yane Yin

Residence Address: No. 168, Science Park 2nd Road  
Hsinchu 300, Taiwan, R.O.C.

Dated: 25 JUL 2012

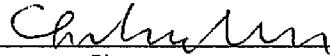
  
Inventor Signature

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Inventor Name: Chi-Hsi Wu

Residence Address: No. 26, Lane 862, Nan-Da Road  
Hsinchu City 300, Taiwan, R.O.C.

Dated: 7/25 2012

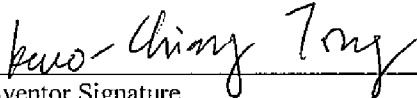
  
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Inventor Name: Kuo-Chiang Ting

Residence Address: 12F-3, No 90, Daxue Road  
Hsinchu City 300, Taiwan, R.O.C.

Dated: 7/25 2012

  
Inventor Signature

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Inventor Name: Kuang-Hsin Chen

Residence Address: 440, Chun-Fu Road  
Jung-Li City, Taiwan, R.O.C.

Dated: 2012/07/25

陳光鑫 Chen, Kuang-hsin  
Inventor Signature

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